



20V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	RDS(ON) MAX	I _{D MAX} T _A = +25°C
	0.6Ω @ $V_{GS} = 4.5V$	1.2A
20V	0.8Ω @ V _{GS} = 2.5V	1.1A
	1.0Ω @ V _{GS} = 1.8V	0.9A

Features

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Low On-Resistance
- ESD Protected Gate
- Wettable Flank for Improved Optical Inspection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- Power-management functions
- General-purpose interfacing switches

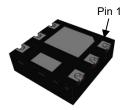
Mechanical Data

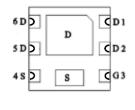
- Package: U-DFN2020-6
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0065 grams (Approximate)

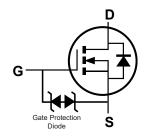
U-DFN2020-6/SWP (Type UXG)











Top View

Bottom View

Pinout Bottom View

Equivalent Circuit

Ordering Information (Note 4)

Orderable Part Number	Package	Packing			
Orderable Part Number	Package	Qty.	Carrier		
DMN2451UFDFW-7	U-DFN2020-6/SWP (Type UXG)	3,000	Tape & Reel		
DMN2451UFDFW-13	U-DFN2020-6/SWP (Type UXG)	10,000	Tape & Reel		

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



CR = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 5 = 2025)

W = Week (ex: a = Week 27; z Represents Weeks 52 and 53)

X = Internal Code (ex: U = Monday)

Date Code Key

Year	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	2036
Code	5	6	7	8	9	0	1	2	3	4	5	6
Week 1-26				27-52			53					
Code	Code A-Z			a-z			Z					
Internal Code	Sur	1	Mon		Tue	W	ed	Thu		Fri		Sat
Code	Т		U		V	V	٧	Х		Υ		Z

Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V_{DSS}	20	V		
Gate-Source Voltage	Vgss	±12	V		
Continuous Drain Current (Note 6) V _{GS} = 4.5V	Steady State	T _A = +25°C T _A = +70°C	lο	1.2 0.7	А
Continuous Drain Current (Note 6) V _{GS} = 2.5V	lο	1.1 0.6	А		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	I _{DM}	3	Α		
Maximum Body Diode Continuous Current (Note 6)	Is	1	Α		

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	PD	0.87	W	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	144	°C/W
Total Power Dissipation (Note 6)		PD	1.39	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	90	°C/W
Thermal Resistance, Junction to Case (Note 6)		Rejc	31	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:



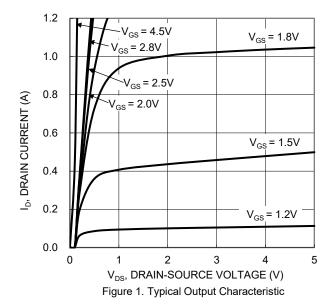
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0$, $I_D = 250 \mu A$	
Zero Gate Voltage Drain Current TJ = +25°C	IDSS	_	_	1	μΑ	V _{DS} = 20V, V _{GS} = 0	
Gate-Source Leakage	Igss	_	_	±1.0	μΑ	V _{GS} = ±4.5V, V _{DS} = 0	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _G S(TH)	0.45	_	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
			0.27	0.6		V _{GS} = 4.5V, I _D = 200mA	
Static Drain-Source On-Resistance	D		0.35	0.8	Ω	V _{GS} = 2.5V, I _D = 200mA	
Static Drain-Source On-Resistance	RDS(ON)	_	0.52	1.0	Ω	V _{GS} = 1.8V, I _D = 100mA	
			0.77	1.6		V _{GS} = 1.5V, I _D = 50mA	
Diode Forward Voltage	V _{SD}	_	0.7	1.2	V	V _{GS} = 0, I _S = 500mA	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	52	_	pF		
Output Capacitance	Coss	_	4.8	_	pF	V _{DS} =16V, V _{GS} = 0, f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	3.1	_	pF	1 – 1.01011 12	
Gate Resistance	Rg	_	95	_	Ω	V _{DS} = 0, V _{GS} = 0 f = 1.0MHz	
Total Gate Charge	Qg	_	0.7	_	nC		
Gate-Source Charge	Qgs	_	0.2	_	nC	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 250mA	
Gate-Drain Charge	Qgd	_	0.1	_	nC	1D - 250MA	
Turn-On Delay Time	t _{D(ON)}	_	3.7	_	ns		
Turn-On Rise Time	t _R	_	2.4	_	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t _{D(OFF)}		20.9		ns	$R_L = 47Ω$, $R_G = 10Ω$, $I_D = 200mA$	
Turn-Off Fall Time	tϝ	_	5.6	_	ns	10 2001111	

Notes:

^{7.} Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.





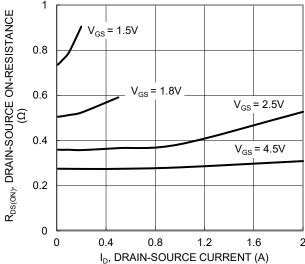


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

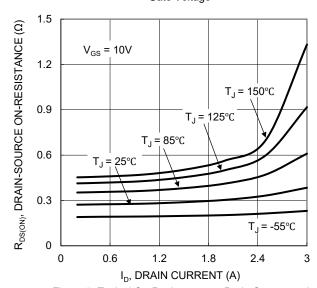
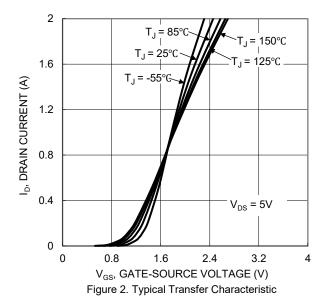


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE $I_{D} = 200 \text{mA}$ 8.0 $I_D = 50 \text{mA}$ 0.6 $\widehat{\mathbf{G}}$ 0.4 0.2 0 0 6 8 10 12 V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 4. Typical Transfer Characteristic

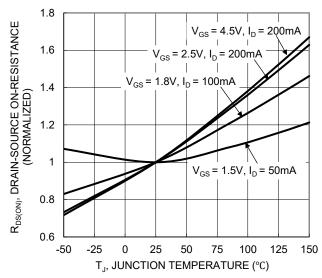


Figure 6. On-Resistance Variation with Temperature





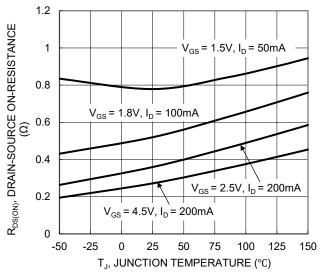


Figure 7. On-Resistance Variation with Temperature

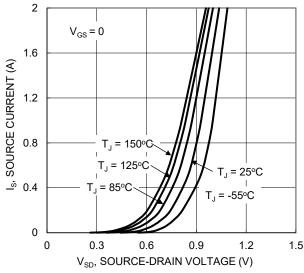


Figure 9. Diode Forward Voltage vs. Current

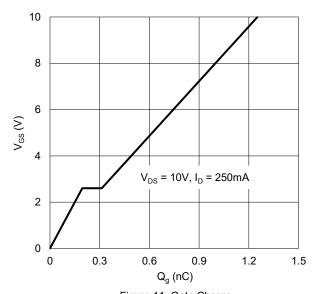


Figure 11. Gate Charge

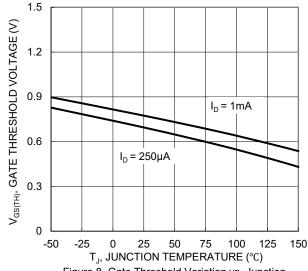
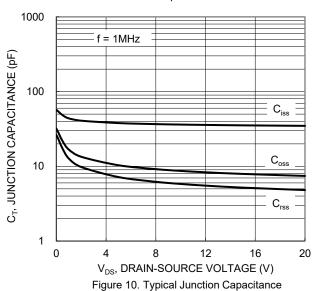


Figure 8. Gate Threshold Variation vs. Junction Temperature



10 R_{DS(ON)} Limited $P_{W} = 100 \mu s$ DRAIN CURRENT (A) 1 $P_W = 100 \text{m/s}$ 0.1 T_{J(Max)} = 150°C T_A = 25℃ ے_ Single Pulse DUT on 1*MRP DC board $V_{GS} = 4.5V$ 0.01 0.1 10 100 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



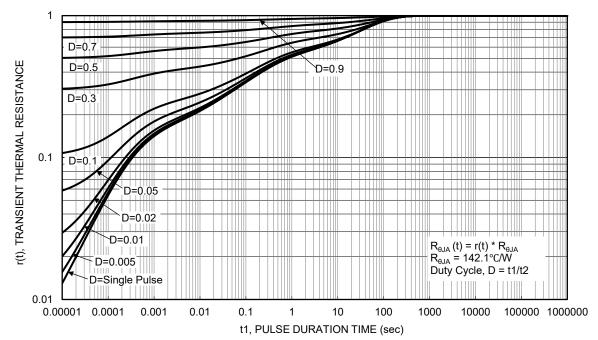


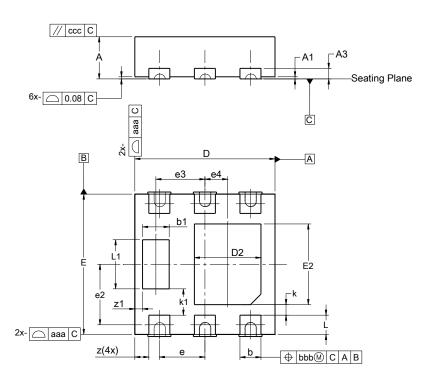
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6/SWP (Type UXG)

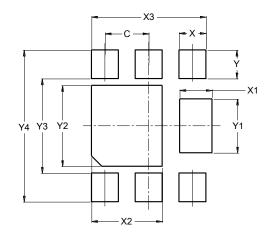


U-DFN2020-6/SWP								
	(Type UXG) Dim Min Max Typ							
Dim	Min	Тур						
Α	0.59	0.65	0.62					
A1	0.00	0.05	0.03					
A3			0.152					
b	0.28	0.38	0.33					
b1	0.35	0.45	0.40					
D	1.95	2.05	2.00					
D2	0.87	1.07	0.97					
Е	1.95	2.05	2.00					
E2	1.07	1.07 1.27 1.17						
е		0.65 BSC						
е3	0.70 BSC							
e4	0	0.325 BSC						
L	0.225	0.225 0.325 0.27						
L1	0.67	0.77	0.72					
k	_	_	0.15					
k1	_	_	0.375					
Z			0.20					
z1			0.11					
aaa		0.25						
bbb		0.10						
CCC	0.10							
All	All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6/SWP (Type UXG)



Dimensions	Value (in mm)
С	0.650
X	0.350
X1	0.480
X2	1.050
Х3	1.700
Y	0.425
Y1	0.800
Y2	1.200
Y3	1.400
Y4	2.250



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